

## ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a semiconductor package, a substrate provided under the semiconductor package, a metal substrate provided on the semiconductor package, and a fixing member positioning the semiconductor package and the metal substrate on the substrate. The substrate is provided with a hole passing though the substrate. A portion of the fixing member is inserted into the hole and a tip of the fixing member contacts a fourth terminal. Semiconductor package has a first main surface, a second main surface provided opposite to the first main surface, and a first terminal provided at the first main surface.